

Prepn. of laminate board for printed circuit board - by heat press  
moulding laminate having woven glass cloth surface layers and nonwoven  
glass cloth interlayer

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Abstract (Basic): JP 1152138 A

Prepn comprises heat press moulding a laminated body consisting of surface layer and interlayer. Surface layer consists of a woven glass cloth impregnated with a varnish obt'd by adding aromatic diamine as curing agent to epoxy resin component with bisphenol A type epoxy resin and novolak type epoxy resin with epoxy equiv 700 1200 and the interlayer consists of a nonwoven glass cloth impregnated with a varnish obt'd by adding Al hydroxide as inorganic filler to the epoxy resin component.

As the bisphenol type epoxy resin, brominated type with bromine content 15-30 wt% is desirable. As the novolak type epoxy resin, bisphenol A novolak type epoxy resin is pref. Amt. of aromatic diamine type curing agent is 0.3-0.7 equiv to epoxy resin. Al hydroxide is 20-200 wt% to interlayer resin.

USE/ADVANTAGE - The laminate board is used for printed circuit, because it has improved high frequency characteristics and drift by moisture uptake and thermal shock resistance due to improved glass transition temp.

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Title Terms: PREPARATION; LAMINATE; BOARD; PRINT; CIRCUIT; BOARD; HEAT; PRESS; MOULD; LAMINATE; WOVEN; GLASS; CLOTH; SURFACE; LAYER; NONWOVEN; GLASS; CLOTH; INTERLAYER

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